



+ CONNECTORS

BOARD-TO-BOARD HEADERS & RECEPTACLES



✓ Active

TE CONNECTIVITY (TE)
MSB0.80PL5ASY56DP,-,10,VCTY
[MICTOR](#) | [MICTOR SB](#)

1-1658013-2
TE Internal Number: 1-1658013-2

[EU RoHS Compliant](#)
[EU ELV Compliant](#)

Connector Style Plug

Connector System Board-to-Board

Number of Positions 56

Centerline (Pitch) .8 mm [.031 in]

Stack Height 5 mm [.197 in]

[↓](#) **PRODUCT DRAWING**
English

[↓](#) **3D PDF**

DOCUMENTATION

Product Drawings

HEADER ASSEMBLY, 5.0MM [.197] VERTICAL, 0.80MM CL,

PDF [\(TIFF AVAILABLE\)](#)

English

CAD Files

Customer View Model

3D_STP.ZIP

English

Customer View Model

2D_DXF.ZIP

English

Customer View Model

3D_IGS.ZIP

English

3D PDF

PDF

English

Product Specifications

Application Specification

MICTOR SB Vertical Connectors For Surface Mount Technology (SMT) Printed Circuit (PC) Board Applications

PDF

English

Product Specification

MICTOR SB (True SMT) Connector

PDF

English

Qualification Test Report

MICTOR SB (True SMT) Connector

PDF

English

Product Environmental Compliance

TE Material Declaration

MD_1-1658013-2_07022016311_dmtec

PDF

English

FEATURES



Please review product documents or [contact us](#) for the latest agency approval information.

Please Note: Use the Product Drawing for all design activity.

Product Type Features

- Connector Style Plug
- Connector System Board-to-Board
- Connector & Contact Terminates To Printed Circuit Board
- Row-to-Row Spacing 4.73 mm [.185889 in]
- Series MICTOR SB
- PCB Mounting Orientation Vertical
- Connector Type Connector Assembly
- Boss With
- Product Type Connector

Configuration Features

- Selectively Loaded Differential Load
- Stackable No
- Number of Positions 56
- Number of Rows 2

Electrical Characteristics

Impedance 50 Ω
Dielectric Withstanding Voltage (VAC) 675
Voltage (VAC) 125
Insulation Resistance (MΩ) 5000

Body Features

Polyamide Film Pad Without

Contact Features

Solder Tail Contact Plating Material Gold over Nickel
Contact Configuration Single Beam
Contact Shape Square
Contact Mating Area Plating Material Select Gold
Contact Mating Area Plating Thickness .25 μm [9.8425 μin]
Contact Current Rating (Max) (A) 1.25, 9.5
Solder Tail Contact Plating Thickness .25 μm [9.8425 μin]
Ground Contact Material Phosphor Bronze
Contact Base Material Phosphor Bronze
Signal Contact Material Phosphor Bronze
Contact Type Pin

Termination Features

Termination Method to PC Board Surface Mount

Mechanical Attachment

Mating Alignment Type Guide Post
PCB Mount Retention Without
PCB Mount Alignment Type Locating Posts

Housing Features

Centerline (Pitch) .8 mm [.031 in]
Housing Material LCP (Liquid Crystal Polymer)
Housing Color Black

Dimensions

Stack Height 5 mm [.197 in]
Height 4.06 mm [.159558 in]

Usage Conditions

Operating Temperature Range -65 – 125 °C [-85 – 257 °F]

Operation/Application

Assembly Process Feature None
Pick and Place Cover Without
For Use With Receptacle Assembly

Packaging Features

Packaging Method Box & Tray, Tray
Packaging Quantity 48

Other

Comment Use of stand offs recommended. Contact Product Engineering for recommendations.

PRODUCT COMPLIANCE



Statement of Compliance

Statement of Compliance
PDF